High Current Surface Mount PNP Silicon Switching Transistor for Load Management in Portable Applications

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	-35	Vdc
Collector-Base Voltage	V _{CBO}	-55	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	I _C	-2.0	Adc
Collector Current - Peak	I _{CM}	-5.0	Α
Electrostatic Discharge	ESD	HBM Class 3 MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation T _A = 25°C	P _D (Note 1)	625	mW	
Derate above 25°C		5.0	mW/°C	
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	200	°C/W	
Total Device Dissipation T _A = 25°C	P _D (Note 2)	1.0	W	
Derate above 25°C		8.0	mW/°C	
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	120	°C/W	
Thermal Resistance, Junction-to-Lead #1	$R_{ hetaJL}$	80	°C/W	
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Notes 2 & 3)	1.75	W	
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

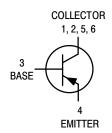
- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 X 1.0 inch Pad
- 3. ref: Figure 9



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35 VOLTS 2.0 AMPS PNP TRANSISTOR



MARKING DIAGRAM



CASE 318G TSOP-6 STYLE 6



M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]		
MBT35200MT1	TSOP-6	3000/Tape & Reel		
MBT35200MT1G	TSOP-6 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-35	-45	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	-55	-65	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	-5.0	-7.0	_	Vdc
Collector Cutoff Current $(V_{CB} = -35 \text{ Vdc}, I_E = 0)$	I _{CBO}	_	-0.03	-0.1	μAdc
Collector–Emitter Cutoff Current (V _{CES} = -35 Vdc)	I _{CES}	-	-0.03	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -4.0 Vdc)	I _{EBO}	_	-0.01	-0.1	μAdc
ON CHARACTERISTICS	•			•	
DC Current Gain $^{(1)}$ (I _C = -1.0 A, V _{CE} = -1.5 V) (I _C = -1.5 A, V _{CE} = -1.5 V) (I _C = -2.0 A, V _{CE} = -3.0 V)	h _{FE}	100 100 100	200 200 200	- 400 -	
Collector – Emitter Saturation Voltage (Note 1.) ($I_C = -0.8 \text{ A}, I_B = -0.008 \text{ A}$) ($I_C = -1.2 \text{ A}, I_B = -0.012 \text{ A}$) ($I_C = -2.0 \text{ A}, I_B = -0.02 \text{ A}$)	V _{CE(sat)}	- - -	-0.125 -0.175 -0.260	-0.15 -0.20 -0.31	V
Base – Emitter Saturation Voltage (Note 1.) $(I_C = -1.2 \text{ A}, I_B = -0.012 \text{ A})$	V _{BE(sat)}	-	-0.68	-0.85	V
Base – Emitter Turn–on Voltage (Note 1.) $(I_C = -2.0 \text{ A}, V_{CE} = -3.0 \text{ V})$	V _{BE(on)}	-	-0.81	-0.875	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	100	_	_	MHz
Input Capacitance (V _{EB} = -0.5 V, f = 1.0 MHz)	Cibo	-	600	650	pF
Output Capacitance ($V_{CB} = -3.0 \text{ V}, f = 1.0 \text{ MHz}$)	Cobo	_	85	100	pF
Turn–on Time (V_{CC} = -10 V, I_{B1} = -100 mA, I_{C} = -1 A, R_{L} = 3 Ω)	t _{on}	-	35	-	nS
Turn-off Time (V_{CC} = -10 V, I_{B1} = I_{B2} = -100 mA, I_{C} = 1 A, R_{L} = 3 Ω)	t _{off}	-	225	-	nS

^{1.} Pulsed Condition: Pulse Width = 300 μ sec, Duty Cycle \leq 2%

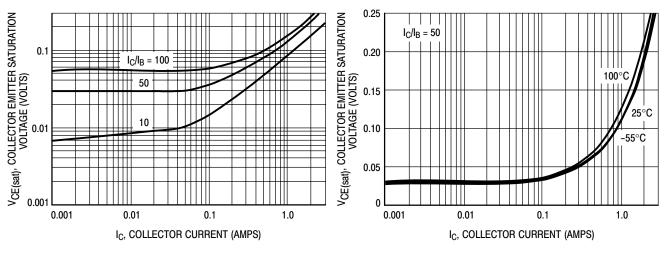


Figure 1. Collector Emitter Saturation Voltage versus Collector Current

Figure 2. Collector Emitter Saturation Voltage versus Collector Current

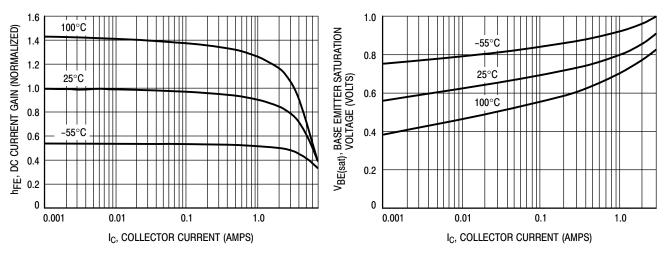


Figure 3. DC Current Gain versus Collector Current

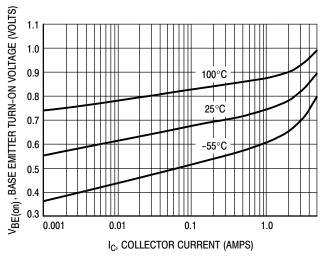


Figure 5. Base Emitter Turn-On Voltage versus Collector Current



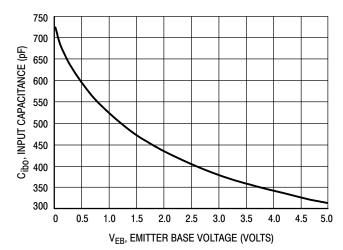


Figure 6. Input Capacitance

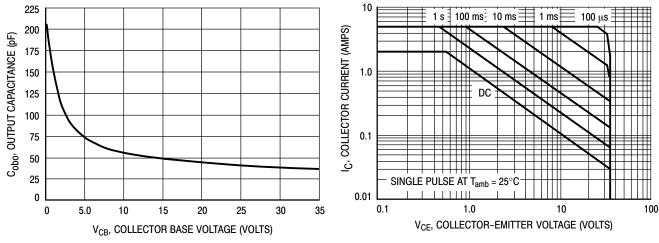


Figure 7. Output Capacitance

Figure 8. Safe Operating Area

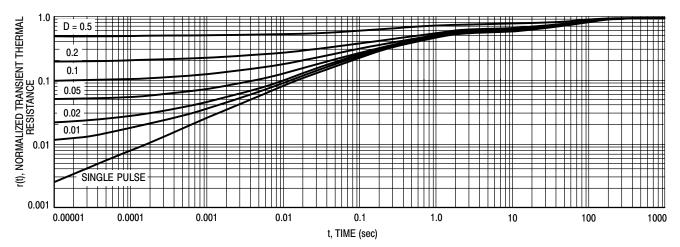
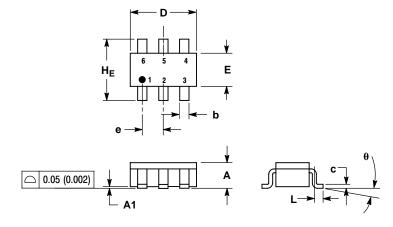


Figure 9. Normalized Thermal Response

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 **ISSUE P**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

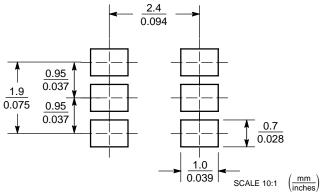
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.38	0.50	0.010	0.014	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
Е	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	_	10°	0°	_	10°	

- STYLE 6:
 PIN 1. COLLECTOR
 2. COLLECTOR
 3. BASE
 4. EMITTER
 5. COLLECTOR
 6. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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